WAFER PROCESSING METHOD

ABSTRACT OF THE DISCLOSURE

Disclosed herein is a wafer processing method including the steps of storing information on the intervals and positions of metal patterns formed on part of division lines on a wafer into a storage unit of a cutting apparatus, detecting the division lines, forming a cut groove along each division line by using a cutting blade, imaging an area including the cut groove at any position where the metal patterns are not formed, by using an imaging unit included in the cutting apparatus, according to the information on the intervals and positions of the metal patterns previously stored, during the step of forming the cut grooves, and measuring the positional relation between the position of the cut groove and a preset cutting position. Accordingly, kerf check can be performed without being influenced by burrs produced from the metal patterns in cutting the wafer, so that the wafer can be cut with high accuracy.

Figure 3A